

D2804, MARCH 1984—REVISED SEPTEMBER 1987

- Full-Carry Look-Ahead Across the Four Bits
- Systems Achieve Partial Look-Ahead Performance with the Economy of Ripple Carry
- Supply Voltage and Ground on Corner Pins to Simplify P-C Board Layout
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

description

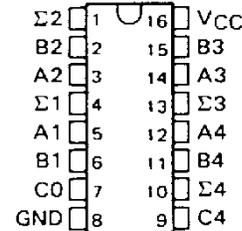
These improved full adders perform the addition of two 4-bit binary words. The sum (Σ) outputs are provided for each bit, and the resultant carry (C4) is obtained from the fourth bit.

These adders feature full internal look-ahead across all four bits generating the carry term. This capability provides the system designer with partial look-ahead performance at the economy and reduced package count of a ripple-carry implementation.

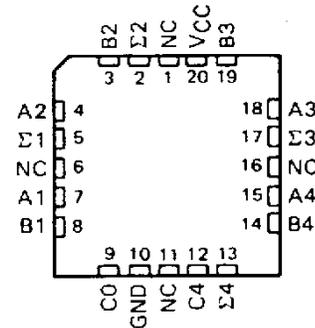
The adder logic, including the carry, is implemented in its true form. End around carry can be accomplished without the need for logic or level inversion.

The SN54HC283 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74HC283 is characterized for operation from -40°C to 85°C .

SN54HC283 . . . J PACKAGE
SN74HC283 . . . D OR N PACKAGE
(TOP VIEW)



SN54HC283 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.


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SN54HC283, SN74HC283
4-BIT BINARY FULL ADDERS WITH FAST CARRY

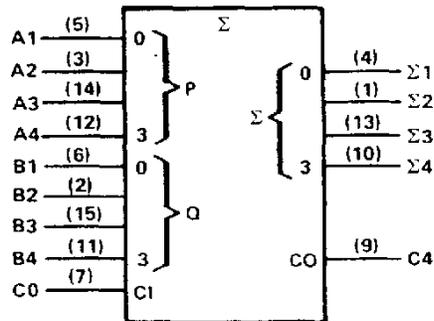
FUNCTION TABLE

INPUT				OUTPUT											
				WHEN C0 = L				WHEN C0 = H							
A1	B1	A2	B2	Σ1	Σ2	C2	Σ1	Σ2	C2	Σ3	Σ4	C4	Σ3	Σ4	C4
L	L	L	L	L	L	L	L	H	L	L	L	L	L	L	L
H	L	L	L	L	H	L	L	L	L	H	L	L	L	L	L
L	H	L	L	L	H	L	L	L	H	L	L	L	L	L	L
H	H	L	L	L	L	H	L	H	H	L	L	L	L	L	L
L	L	H	L	L	L	H	L	L	H	L	L	L	L	L	L
H	L	H	L	L	H	H	L	L	L	L	L	L	L	L	L
L	H	H	L	L	H	H	L	L	L	L	L	L	L	L	L
H	H	H	L	L	L	L	H	H	H	L	L	L	L	L	L
L	L	L	H	L	L	H	L	L	H	L	L	L	L	L	L
H	L	L	H	L	H	H	L	L	L	L	L	L	L	L	L
L	H	L	H	L	H	H	L	L	L	L	L	L	L	L	L
H	H	L	H	L	L	L	H	H	L	L	L	L	L	L	L
L	L	H	H	L	L	L	H	H	L	L	L	L	L	L	L
H	L	H	H	L	H	L	H	L	L	L	L	L	L	L	L
L	H	H	H	L	H	L	H	L	L	L	L	L	L	L	L
H	H	H	H	L	L	H	H	L	L	L	L	L	L	L	L

H = high level, L = low level

NOTE: Input conditions at A1, B1, A2, B2, and C0 are used to determine outputs Σ1 and Σ2 and the value of the internal carry C2. The values at C2, A3, B3, A4, and B4 are then used to determine outputs Σ3, Σ4, and C4.

logic symbol†

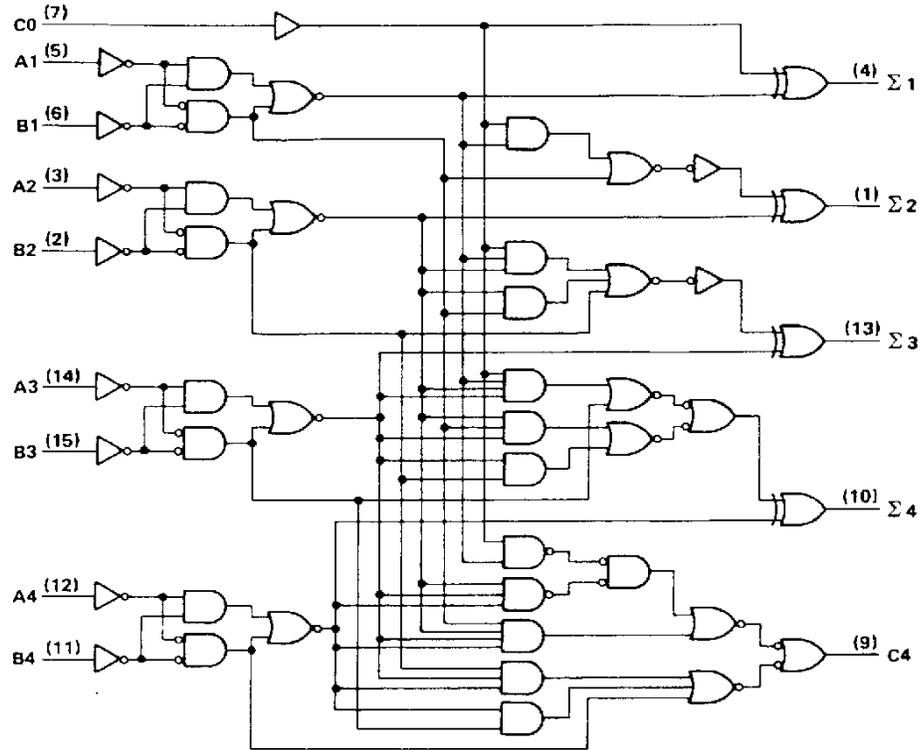


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

SN54HC283, SN74HC283
4-BIT BINARY FULL ADDERS WITH FAST CARRY

logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

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SN54HC283, SN74HC283
4-BIT BINARY FULL ADDERS WITH FAST CARRY

absolute maximum ratings over operating free-air temperature range†

Supply voltage, V_{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND pins	± 50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package	300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package	260°C
Storage temperature range	-65°C to 150°C

†Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54HC283			SN74HC283			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V		1.5	$V_{CC} = 2$ V		1.5	V
		$V_{CC} = 4.5$ V		3.15	$V_{CC} = 4.5$ V		3.15	
		$V_{CC} = 6$ V		4.2	$V_{CC} = 6$ V		4.2	
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0	0.3	$V_{CC} = 2$ V		V
		$V_{CC} = 4.5$ V		0	0.9	$V_{CC} = 4.5$ V		
		$V_{CC} = 6$ V		0	1.2	$V_{CC} = 6$ V		
V_I	Input voltage	0		V_{CC}	0		V_{CC}	V
V_O	Output voltage	0		V_{CC}	0		V_{CC}	V
t_t	Input transition (rise and fall) times	$V_{CC} = 2$ V		0	1000	$V_{CC} = 2$ V		ns
		$V_{CC} = 4.5$ V		0	500	$V_{CC} = 4.5$ V		
		$V_{CC} = 6$ V		0	400	$V_{CC} = 6$ V		
T_A	Operating free-air temperature	-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC283			SN74HC283			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL} , $I_{OH} = -20 \mu\text{A}$	2 V	1.9	1.998		1.9		1.9			V	
		4.5 V	4.4	4.499		4.4		4.4				
		6 V	5.9	5.999		5.9		5.9				
V_{OL}	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 20 \mu\text{A}$	4.5 V	3.98	4.30		3.7		3.84			V	
		6 V	5.48	5.80		5.2		5.34				
		2 V		0.002	0.1		0.1		0.1			
V_{OL}	$V_I = V_{IH}$ or V_{IL} , $I_{OL} = 4 \text{ mA}$	4.5 V		0.001	0.1		0.1		0.1		V	
		6 V		0.001	0.1		0.1		0.1			
		4.5 V		0.17	0.26		0.4		0.33			
I_I	$V_I = V_{CC}$ or 0	6 V		± 0.1	± 100		± 1000		± 1000		nA	
		6 V					8		160		μA	
I_{CC}	$V_I = V_{CC}$ or 0, $I_O = 0$	6 V								80	μA	
C_i		2 to 6 V		3	10		10			10	pF	



SN54HC283, SN74HC283
4-BIT BINARY FULL ADDERS WITH FAST CARRY

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), $C_L = 50$ pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25 °C			SN54HC283		SN74HC283		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	C0	Any Σ	2 V	60	150		225		188	ns	
			4.5 V	20	30		45		37		
			6 V	16	26		38		32		
t _{pd}	A _i or B _i	Σ _i	2 V	80	175		262		218	ns	
			4.5 V	25	35		52		44		
			6 V	20	30		45		37		
t _{pd}	C0	C4	2 V	70	175		262		218	ns	
			4.5 V	25	35		52		44		
			6 V	20	30		45		37		
t _{pd}	A _i or B _i	C4	2 V	90	175		262		218	ns	
			4.5 V	26	35		52		44		
			6 V	21	30		45		37		
t _t		Any	2 V	28	75		110		95	ns	
			4.5 V	8	15		22		19		
			6 V	6	13		19		16		

C _{pd}	Power dissipation capacitance	No load, T _A = 25 °C	90 pF typ
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NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC283D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74HC283DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74HC283N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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